# **MMVL3102T1**

Preferred Device

# **Silicon Tuning Diode**

This device is designed in the Surface Mount package for general frequency control and tuning applications. It provides solid–state reliability in replacement of mechanical tuning methods.

#### **Features**

- High Q with Guaranteed Minimum Values at VHF Frequencies
- Controlled and Uniform Tuning Ratio
- Pb-Free Package is Available

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V <sub>R</sub>	30	Vdc
Peak Forward Current	IF	200	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, T <sub>A</sub> = 25°C (Note 1) Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-4 Minimum Pad



# ON Semiconductor®

http://onsemi.com

# 22 pF (Nominal) 30 VOLTS VOLTAGE VARIABLE CAPACITANCE DIODE





PLASTIC SOD-323 CASE 477 STYLE 1

# **MARKING DIAGRAM**



4C = Device Code M = Date Code\*

= Pb–Free Package

(Note: Microdot may be in either location)
\*Date Code orientation may vary depending upon manufacturing location.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMVL3102T1	SOD-323	3000 / Tape & Reel
MMVL3102T1G	SOD-323 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

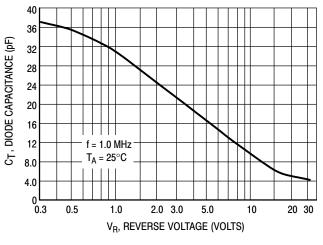
**Preferred** devices are recommended choices for future use and best overall value.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage $(I_R = 10 \mu Adc)$	V <sub>(BR)R</sub>	30	_	-	Vdc
Reverse Voltage Leakage Current (V <sub>R</sub> = 25 Vdc, T <sub>A</sub> = 25°C)	I <sub>R</sub>	-	-	0.1	μAdc
Diode Capacitance Temperature Coefficient (V <sub>R</sub> = 4.0 Vdc, f = 1.0 MHz)	TC <sub>C</sub>	_	300	-	ppm/°C

	C <sub>t</sub> , Diode Capacitance V <sub>R</sub> = 3.0 Vdc, f = 1.0 MHz pF		Q, Figure of Merit V <sub>R</sub> = 3.0 Vdc f = 50 MHz	C <sub>3</sub> /	C <sub>R</sub> , Capacitance Ratio C <sub>3</sub> /C <sub>25</sub> f = 1.0 MHz	
Device	Min Nom Max		Min	Min	Тур	
MMVL3102T1	20	22	25	200	4.5	4.8

## **TYPICAL CHARACTERISTICS**



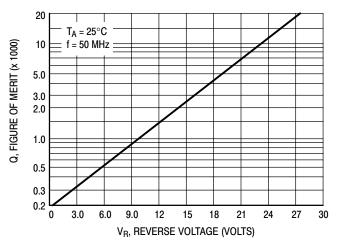
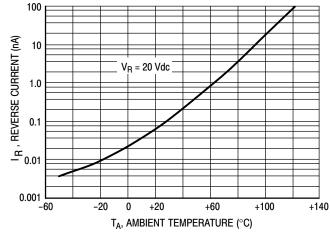


Figure 1. Diode Capacitance

Figure 2. Figure of Merit



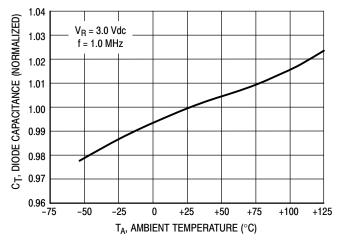


Figure 3. Leakage Current

Figure 4. Diode Capacitance

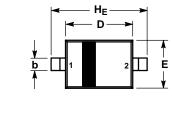
# NOTES ON TESTING AND SPECIFICATIONS

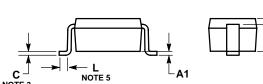
 $C_{R}$  is the ratio of  $C_{T}$  measured at 3.0 Vdc divided by  $C_{T}$  measured at 25 Vdc.

## MMVL3102T1

#### PACKAGE DIMENSIONS

SOD-323 CASE 477-02 ISSUE G





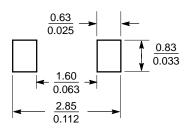
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
   V14 FM 1082
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETERS.
- LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.031	0.035	0.040	
A1	0.00 0.05 (		0.10	0.000	0.002	0.004	
A3	(	).15 REI	F	0.006 REF			
b	0.25 0.32		0.4	0.010	0.012	0.016	
С	0.089	0.12	0.177	0.003	0.005	0.007	
D			1.80	0.062	0.066	0.070	
Е			1.35	0.045	0.049	0.053	
L				0.003			
HE	2.30	2.50	2.70	0.090	0.098	0.105	

STYLE 1: PIN 1. CATHODE 2. ANODE

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.